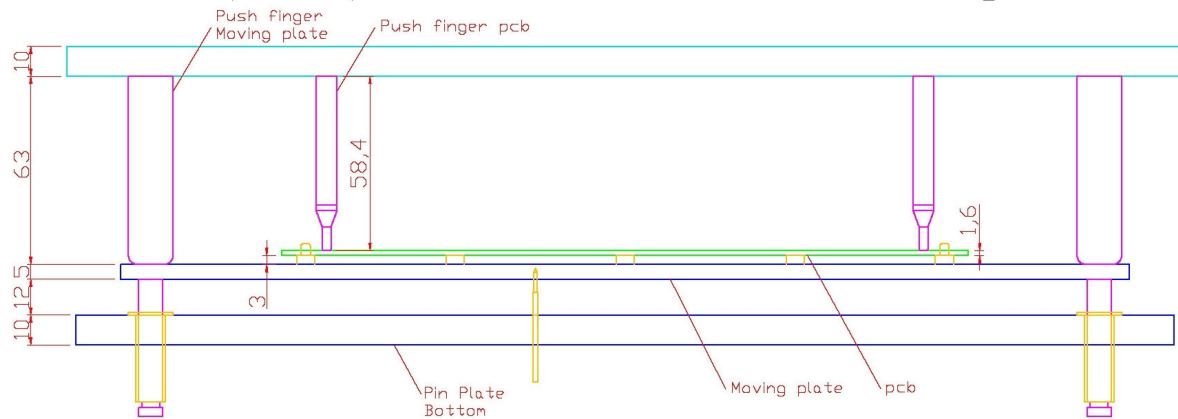


Dimensions for the 6TL01, 6TL02, 6TL03 and 6TL08 Cassette kit



Open position - No contacting



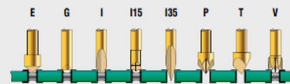
Pads
Some applications require a non aggressive tip like the D, J or F type tip. These tips leave no marks or footprints on the test pads. Other applications may need to break through oxide layers, OSP or other contaminations. For these test points the B, E, J, L, T and U tip with their medium to very aggressive geometry penetrate through the contaminations and offer best first pass contact.



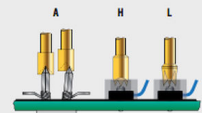
Solder Pads, Solder Balls
Over time solder build up oxide layers, therefore medium to very aggressive tip geometries are used. H-INS or HM-INS Tip - The tip geometry is designed with a pin present detection. If a component lead is not soldered correctly and fully into the PCB board, the insulating ring around the H tip will act as a collar, preventing the conductive probe tip from making contact with the faulty test point.



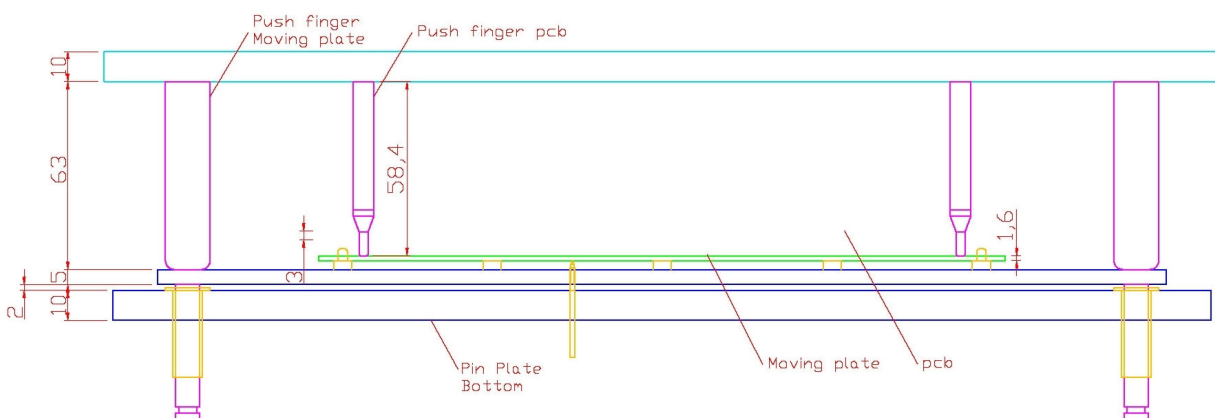
Vias
Typical tips are used that center themselves into the via hole. ECT offers a variety of different I tip angles, which are used to accommodate through-hole vias as well as solder filled holes. Other Tips like the G or V tip are suited to contact only the outer ring of the vias on the board surface.



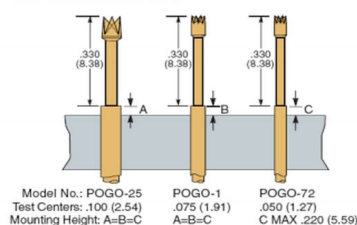
Posts, Pins and Screws
For other applications like posts, pins or screws are more unpredictable and therefore more challenging to select the best tip style. Posts and pins are captured with tips like the A, H or L Tip. Other applications depending on material, size, shape, access or clearance, contamination and so on may require other tips.



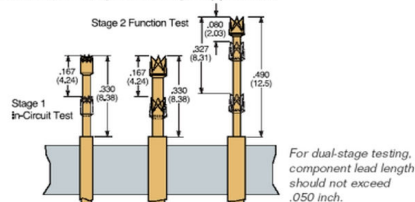
Closed position - Bottom contacting



SMT and Loaded Board



Loaded Board Testing Dual-Stage Application



Nr.	Material	Aantal
Onderdeel: Niveaus Testfixtures		
Tekening nummer:		MG
Getekend:		M van Daal
Datum:		26-6-2012
Formaat:		A3
Schaal:		1:1

